

## PROJECT ADMINISTRATION DATA SHEET

Project No. A-3245 ☒ ORIGINAL ☐ REVISION NO. 5-7-82  
 Project Director: S.F. KANEY School/Lab SEL  
 Sponsor: USAF, Warner Robins ALC, Robins AFB, GA 31098

Type Agreement: Delivery Order 0005 under BOA F09603-82-G-3367

Award Period: From 4-15-82 To 10-15-82 (Performance) 10-15-82 (Reports)

Sponsor Amount: \$10,000 12/31/83 Contracted through:

Cost Sharing: None

GTRI/~~OT~~

Title: Bare Base Chemical Toilet Circuit Card Assemblies

## ADMINISTRATIVE DATA

OCA Contact Don Hasty

1) Sponsor Technical Contact:

Anthony M. White or  
Keith DAMMANN  
WR-ALC/MMIRDA

2) Sponsor Admin/Contractual Matters:

T. Bryant  
ONR-IRR  
Campus

(912) 926-6194 (White)  
" " -2809 (Dammann)

881-4213

Defense Priority Rating: DO-C 92 under  
DMS Reg 1

Security Classification: N/A

## RESTRICTIONS

See Attached DOD Supplemental Information Sheet for Additional Requirements.

Travel: Foreign travel must have prior approval - Contact OCA in each case. Domestic travel requires sponsor approval where total will exceed greater of \$500 or 125% of approved proposal budget category.

Equipment: Title vests with Government; however, none proposed

## COMMENTS:

Per Diem/Travel costs cannot exceed limits of  
referenced joint Travel Regulations-

## COPIES TO:

et Admin Network  
 Administrative Coordinator  
 Research Property Management  
 Accounting  
 Procurement/EES Supply Services  
 FORM OCA 4:781

Research Security Services  
~~Reports Coordinator (OCA)~~  
 Legal Services (OCA)  
 Library

EES Public Relations  
 Computer Input  
 Project File  
 Other



SPONSORED PROJECT TERMINATION SHEETDate 8/29/83

Project Title: Bare Base Chemical Toilet Circuit Cord Assemblies

Project No: A-3245

Project Director: S. F. Kaney

Sponsor: USAF, Warner Robins ALC, Robins AFB, GA 31098

Effective Termination Date: 10/15/82Clearance of Accounting Charges: 10/15/82

Grant/Contract Closeout Actions Remaining:

- ☒ Final Invoice ~~and Closing Documents~~
- ☐ Final Fiscal Report
- ☒ Final Report of Inventions (Patent Questionnaire attached for Project Director)
- ☒ Govt. Property Inventory & Related Certificate
- ☐ Classified Material Certificate
- ☐ Other \_\_\_\_\_

Assigned to: SEL (School/Laboratory)COPIES TO:

<del>Administrative Coordinator</del>	Research Security Services	EES Public Relations (2)
Research Property Management	<del>Reports Coordinator (OCA)</del>	Computer Input
Accounting	Legal Services (OCA)	Project File
Procurement/EES Supply Services	Library	Other <u>S. F. Kaney</u>

**ENGINEERING ANALYSIS  
OF  
BARE BASE CHEMICAL TOILET  
CIRCUIT CARD ASSEMBLIES  
P/N 103717 and P/N 103718**

**Prepared for  
Warner Robins Air Logistics Center  
MMIRDA  
Warner Robins, Ga.**

**Engineering Experiment Station  
Georgia Institute of Technology  
Atlanta, Ga. 30332**

## TABLE OF CONTENTS

<u>SECTION</u>	<u>TITLE</u>	<u>PAGE</u>
I	PURPOSE . . . . .	1
II	PROJECT ACTIVITIES AND PROCEDURES . . . . .	2
III	COMPONENT SPECIFICATIONS . . . . .	3
IV	BOARD SPECIFICATIONS . . . . .	8
V	MANUFACTURING TECHNIQUES . . . . .	13
VI	TROUBLESHOOTING PROCEDURES . . . . .	18
VII	COMPONENT TESTING . . . . .	19
VIII	CIRCUIT CARD FUNCTIONAL ANALYSIS . . . . .	21
IX	PROPOSED IMPROVEMENTS . . . . .	25



# LIST OF ILLUSTRATIONS

<u>FIGURE</u>	<u>TITLE</u>	<u>PAGE</u>
1	COMPONENT SIDE VIEW 103717 . . . . .	4
2	COMPONENT SIDE VIEW 103718 . . . . .	5
3	SCHEMATIC 103717 . . . . .	6
4	SCHEMATIC 103718 . . . . .	7
5	DRILL CHART FOR 103717 . . . . .	9
6	DRILL CHART FOR 103718 . . . . .	10
7	MECHANICAL DRAWING FOR P/N 103717 . . . . .	11
8	MECHANICAL DRAWING FOR P/N 103718 . . . . .	12
9	FOIL SIDE VIEW FOR P/N 103717 . . . . .	14
10	FOIL SIDE VIEW FOR P/N 103718 . . . . .	15
11	SOLDER MASK FOR P/N 103717 . . . . .	16
12	SOLDER MASK FOR P/N 103718 . . . . .	17
13	FUNCTIONAL BLOCK DIAGRAM FOR P/N 103717 . . . . .	22
14	FUNCTIONAL BLOCK DIAGRAM FOR P/N 103718 . . . . .	23

## I. PURPOSE

The purpose of this report is to provide a functional description of two circuit card assemblies P/N 103717 (12 second timer) and 103718 (Logic Control) and to provide the necessary engineering data for procuring the circuit boards.

The following information is provided in this report:

- A complete parts list of both boards
- A complete manufacturing specification for each board and each individual component
- Drawings and manufacturing techniques for each board
- Soldering and plating diagrams for each board
- Trouble shooting procedure for damaged circuit board
- Suggested improvements

## II. PROJECT ACTIVITIES AND PROCEDURES

The basic project objective was to reverse-engineer two circuit card assemblies used in the electronic control box of the Bare Base Chemical Toilet. After receiving one sample of each of the circuit card assemblies, engineering analysis of each of the cards began. This engineering analysis included a detailed description of the circuit cards' functions, complete component identification, including military specifications and available vendors, descriptions of the mechanical layout of each card, and all other data necessary to document the circuit card assemblies in order to provide a complete procurement package. This information was collected and organized and forms the basis of this report.

Also, as a secondary effort, damaged circuit cards were repaired and returned to the sponsor to increase the available working inventory.

### III. COMPONENT SPECIFICATIONS

Component specifications for each board (see Figures 1 and 2) are listed with the requested Military Specifications numbers and component locations. The capacitors, resistors, and transistors are standard components and can be purchased from various electronic distributors (e.g., Hamilton-Avenet, Schweber, Arrow, Marshall, etc.). The printed circuit contacts on both boards are special purpose board-to-board contacts and are manufactured by Elco Connector Division.\* Board No. 103717 (12 second timer) has a DPDT (double-pole double-throw), 10 amp contact, relay that can be procured from Airpax Corporation.\*\* Board No. 103718 (Logic Control) has two relays that can be procured from General Electric.\*\*\*

Circuit schematics for each board are also provided (see Figures 3 and 4) to show the functions and relations of the electronic components found on each board. A detailed circuit functional analysis of each board is provided in Section VIII.

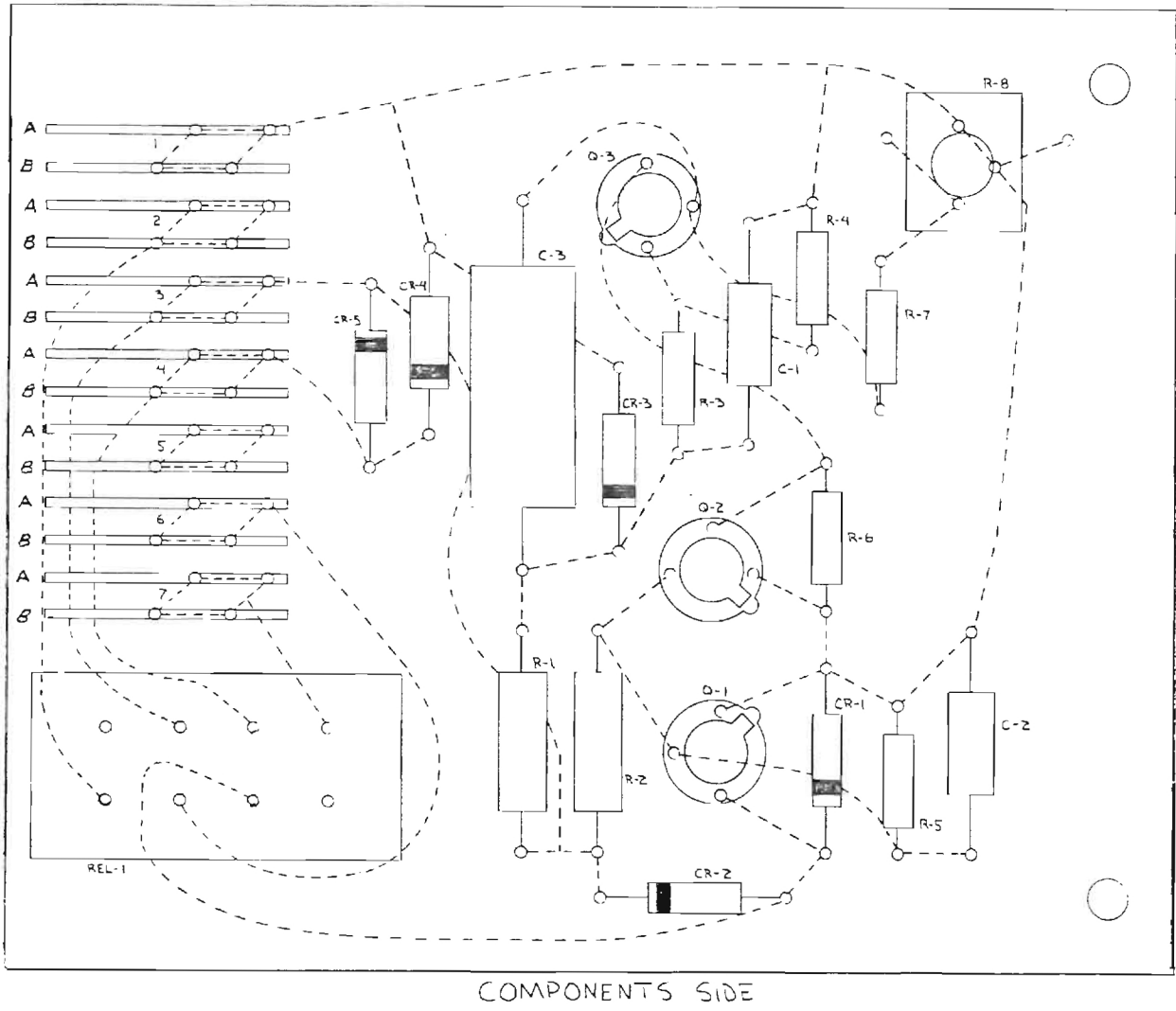
\* ELCO, Electronic Connector Division  
Huntingdon Industrial Park  
Huntingdon, PA 16652  
(814) 643-0700

\*\* Airpax Corporation, North American Philips Co.  
Frederick Division  
Husky Park, Frederick, MD 21701  
(301) 663-5141

\*\*\* General Electric  
Electronic Component Sales Department  
1835 Savoy Dr.  
Atlanta, GA  
(404) 458-8401

APPLICATION		REVISIONS		DATE		APPROVED	
QTY REQD	NEXT ASSY	USED ON	ZONE	SYM	DESCRIPTION	DATE	APPROVED

NOTE: \* AS PER MIL-R-39008  
 \*\* AS PER MIL-C-39003/1B  
 \*\*\* ALSO TO MIL-R-M5757/23 AND 6106



Q-1	1	TRANSISTOR	2N2222	JAN2N2222A
Q-2	1	TRANSISTOR	2N2222	JAN2N2222A
Q-3	1	TRANSISTOR	2N207A	JAN2N207A
CR-1	1	DIODE	1N979A	JAN1N979A
CR-2	1	DIODE	1N649	JAN1N649
CR-3	1	DIODE	1N757A	JAN1N757A
CR-4	1	DIODE	1N4946	JAN1N4946
CR-5	1	DIODE	1N649	JAN1N649
R-1	1	RESISTOR	3300 $\Omega$ 1/2 Watt	*RCR07G332KM
R-2	1	RESISTOR	3300 $\Omega$ 1/2 Watt	*RCR07G332KM
R-3	1	RESISTOR	2700 $\Omega$ 1/4 Watt	*RCR05G272KM
R-4	1	RESISTOR	2700 $\Omega$ 1/4 Watt	*RCR05G272KM
R-5	1	RESISTOR	2700 $\Omega$ 1/4 Watt	*RCR05G272KM
R-6	1	RESISTOR	10K $\Omega$ 1/4 Watt	*RCR05G103KM
R-7	1	RESISTOR	220K $\Omega$ 1/4 Watt	*RCR05G224KM
R-8	1	POTENTIOMETER	200K $\Omega$ POT 249.11	*RIR32F201M
C-1	1	CAPACITOR	1 $\mu$ F	**CSR13G105ML
C-2	1	CAPACITOR	1 $\mu$ F	**CSR13G105ML
C-3	1	CAPACITOR	47 $\mu$ F	**CSR13E476MM
REL-1	1	RELAY	607A03BC1	*** TO MIL-R-5757
1-7B	7	P.C. CONTACT	5203-147	
1-7A	7	P.C. CONTACT	5203-137	

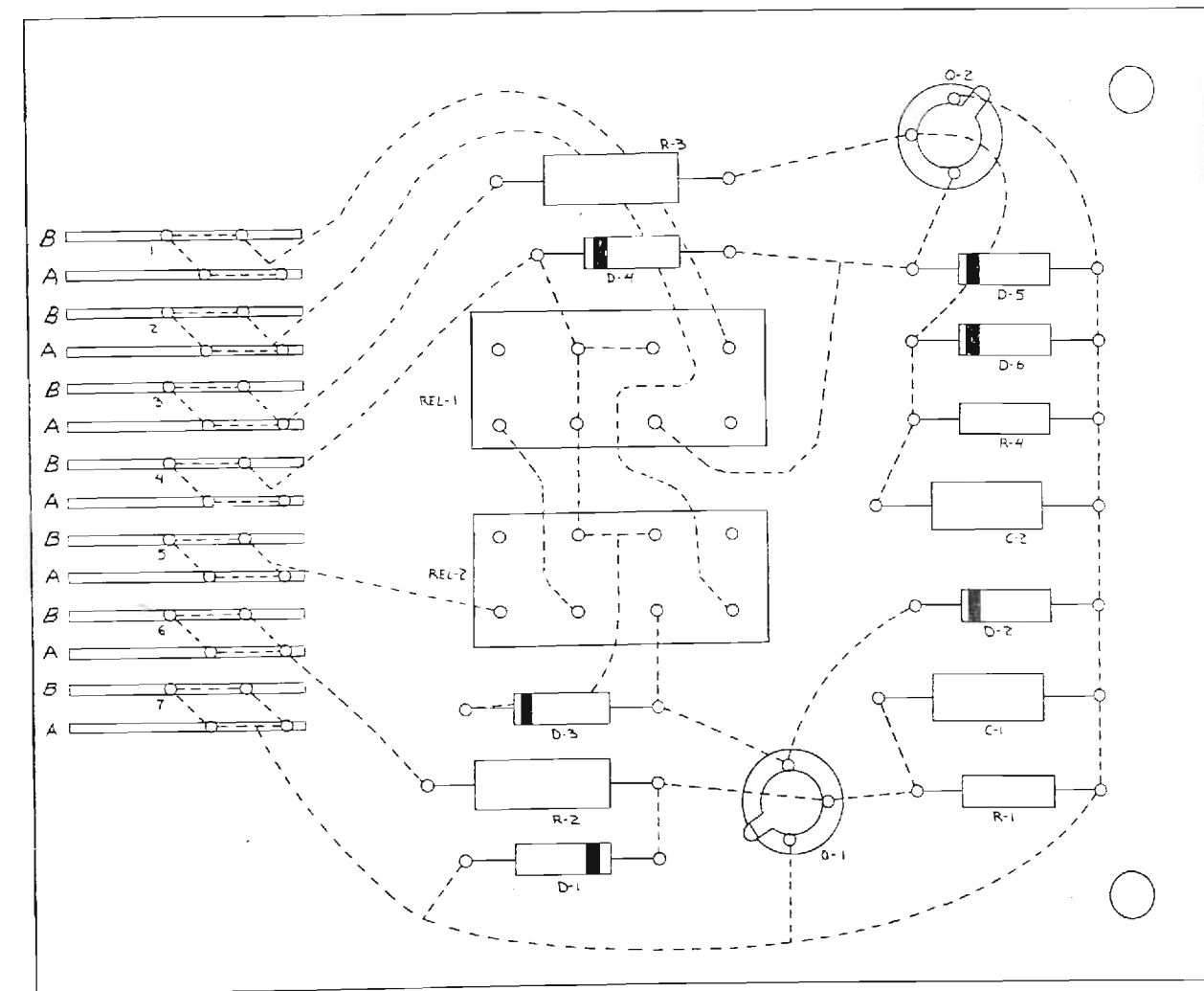
ITEM OR FIND NO.	QTY REQD	NOMENCLATURE OR DESCRIPTION	MATL SPEC AND SIZE OR COMPONENT VALUE	IDENTIFYING OR PART NO.	CODE IDENT.
PARTS LIST					
ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE SPECIFIED 3 PLACE DECIMALS ± 2 PLACE DECIMALS ± 1 PLACE DECIMAL ± FRACTIONS ±    ANGLES ± 0°30' MAX SURFACE ROUGHNESS 125 ALL MACHINED SURFACES EXCEPT AS NOTED BREAK SHARP EDGES AND CORNERS .010 MAX FINISH		CONT NO CHG NO DWN P. WARREN 63 82 ENGR CHK PROD APVD APVD	ENGINEERING EXPERIMENT STATION GEORGIA INSTITUTE OF TECHNOLOGY ATLANTA, GEORGIA <b>COMPONENT SIDE</b> <b>CIRCUIT CARD ASSEMBLY</b> <b>P/N 103717</b> SIZE D    CODE IDENT NO. 07101    DRAWING NO. A-3245-004 SCALE /    FIGURE # 1    SHEET		

FIGURE #1

COMPONENT SIDE VIEW  
 P/N 103717

APPLICATION			REVISIONS		
QTY REQD	NEXT ASSY	USED ON	ZONE	SYM	DESCRIPTION

NOTE: \* AS PER MIL-R-39008  
 \*\* AS PER MIL-C-39002/1B

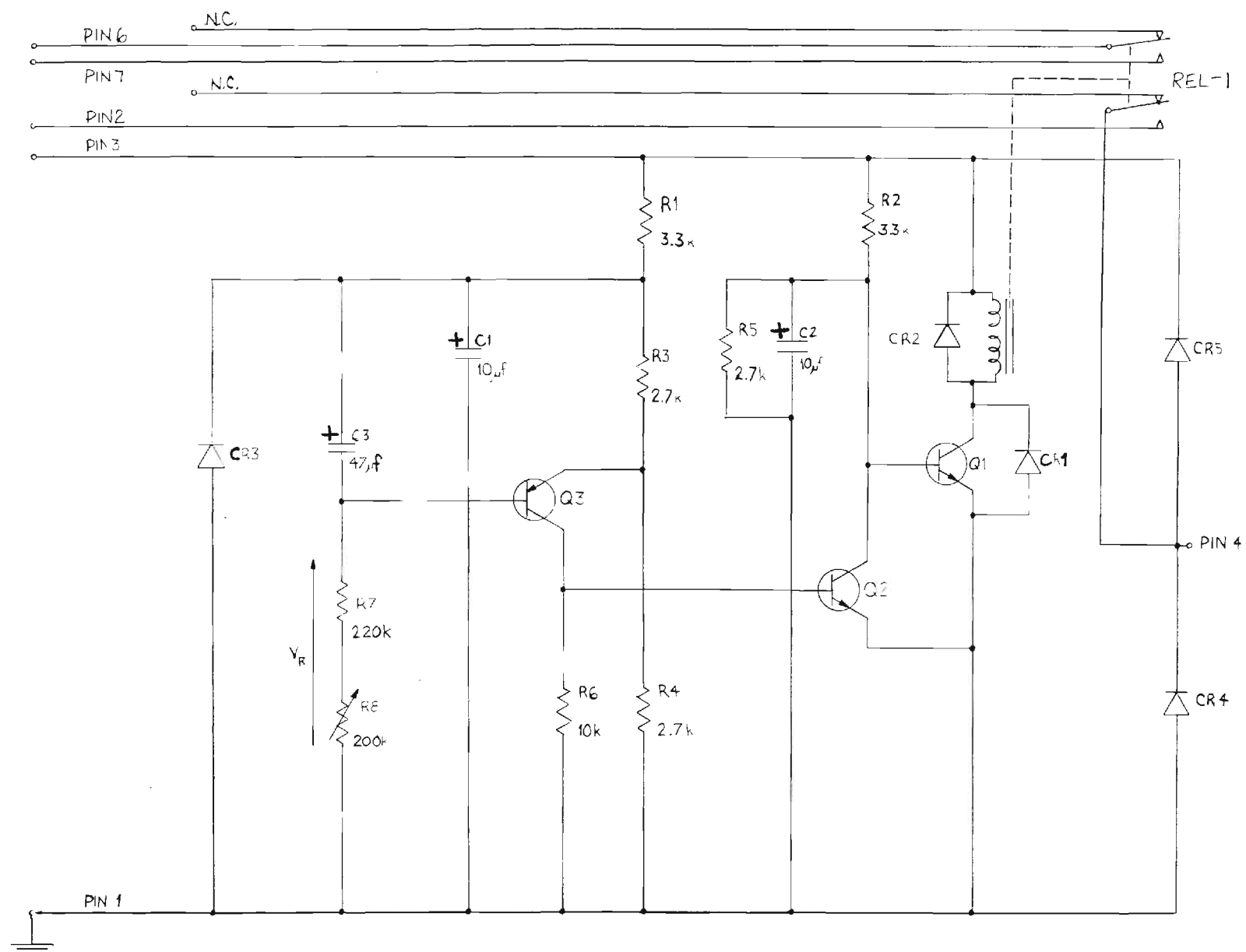


COMPONENTS SIDE

D-1	1	DIODE	1N4833	JANIN483B
D-2	1	DIODE	1N979A	JANIN979A
D-3	1	DIODE	1N649	JANIN649
D-4	1	DIODE	1N649	JANIN649
D-5	1	DIODE	1N979A	JANIN979A
D-6	1	DIODE	1N483B	JANIN483B
R-1	1	RESISTOR	470Ω 1/4 Watt	*RCR05G471KM
R-2	1	RESISTOR	5.6KΩ 1/2 Watt	*RCR07G562KM
R-3	1	RESISTOR	5.6KΩ 1/2 Watt	*RCR07G563KM
R-4	1	RESISTOR	470Ω 1/4 Watt	*RCR05G471KM
C-1	1	CAPACITOR	1μF	**CSR13G105PIL
C-2	1	CAPACITOR	1μF	**CSR13G105ML
REL-1	1	RELAY	GE 3SAV2109AZ	TO MIL-R-5757/9
REL-2	1	RELAY	GE 3SAV2109AZ	TO MIL-R-5757/9
Q-1	1	TRANSISTOR	2N2222A	JAN2N2222A
Q-2	1	TRANSISTOR	2N2222A	JAN2N2222A
I-7B	7	P.C. CONTACT	5203-147	
I-7A	7	P.C. CONTACT	5203-137	

ITEM OR FIND NO.	QTY REQD	NOMENCLATURE OR DESCRIPTION	MATL SPEC AND SIZE OR COMPONENT VALUE	IDENTIFYING OR PART NO.	CODE IDENT.
PARTS LIST					
ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE SPECIFIED		CONT NO	ENGINEERING EXPERIMENT STATION OF THE GEORGIA INSTITUTE OF TECHNOLOGY ATLANTA, GEORGIA		
TOLERANCES		CHG NO	EES		
3 PLACE DECIMALS ±		DWN P. WARREN	5-27-82	COMPONENT SIDE	
2 PLACE DECIMALS ±		ENGR		CIRCUIT CARD ASSEMBLY	
1 PLACE DECIMAL ±		CHK		P/N 103718	
FRACTIONS ±		PROD			
ANGLES ± 0° 30'		APVD		SIZE	CODE IDENT NO.
MAX SURFACE ROUGHNESS 125		APVD		D	07101
ALL MACHINED SURFACES EXCEPT AS NOTED BREAK SHARP EDGES AND CORNERS .010 MAX				DRAWING NO.	A-3245-002
FINISH				SCALE	FIGURE #2
					SHEET

FIGURE #2  
 COMPONENT SIDE VIEW



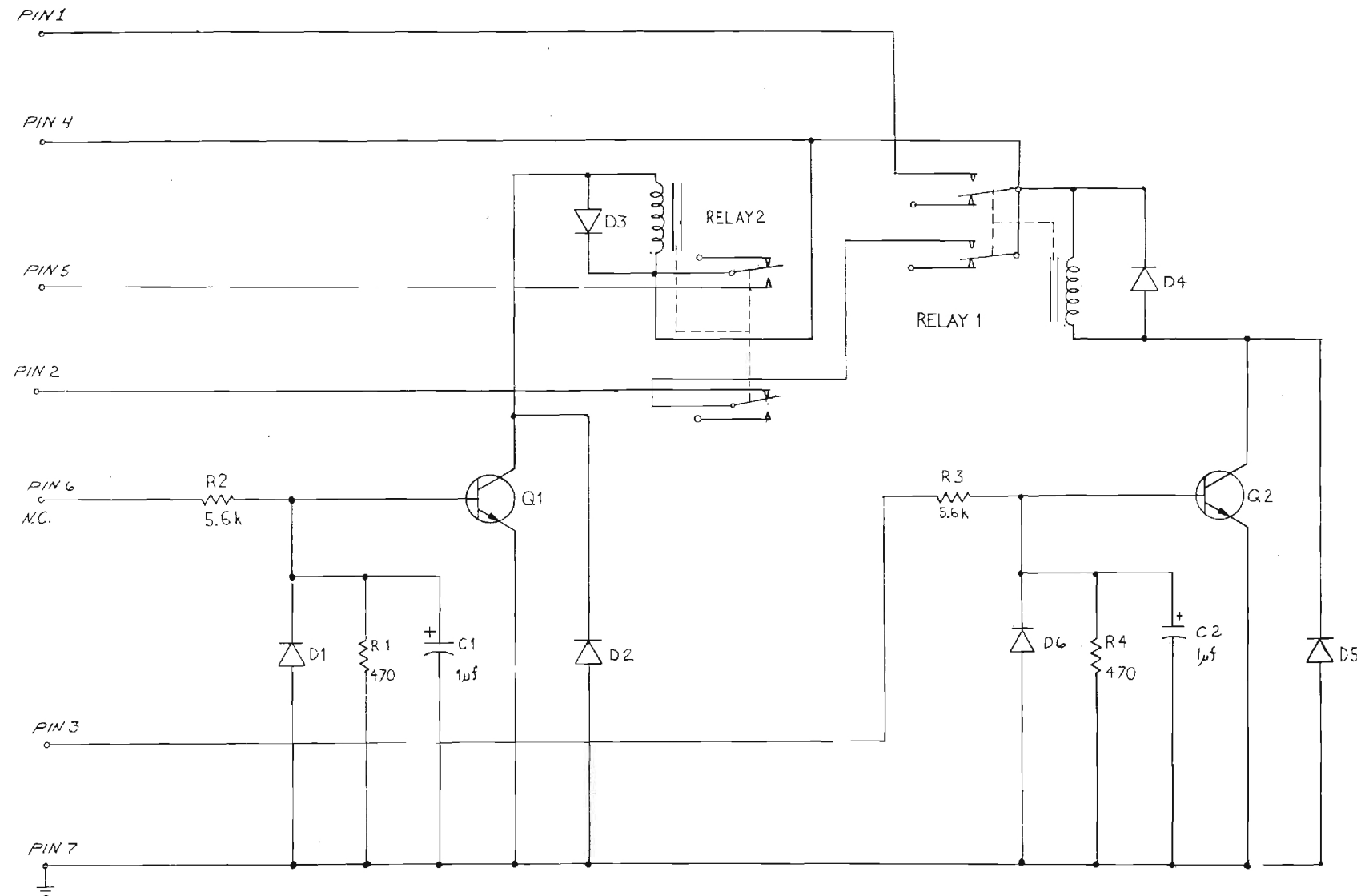
NOTE: RELAYS SHOWN IN  
DE-ENERGIZED POSITION

FIGURE #3  
SCHEMATIC  
P/N 103717

APPLICATION			REVISIONS			
QTY REQD	NEXT ASSY	USED ON	ZONE	SYM	DESCRIPTION	DATE

ITEM OR FIND NO.	QTY REQD	NOMENCLATURE OR DESCRIPTION	MATL SPEC AND SIZE OR COMPONENT VALUE	IDENTIFYING OR PART NO.	CODE IDENT.
PARTS LIST					
ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE SPECIFIED		CONT NO	<b>ENGINEERING EXPERIMENT STATION</b> OF THE <b>GEORGIA INSTITUTE OF TECHNOLOGY</b> ATLANTA, GEORGIA		
TOLERANCES		CHG NO			
3 PLACE DECIMALS ±		DWN RC JULIAN			
2 PLACE DECIMALS ±		ENGR			
1 PLACE DECIMAL ±		CHK			
FRACTIONS ±		PROD	<b>SCHEMATIC</b> <b>CIRCUIT CARD P/N 103717</b> <b>12 SECOND TIMER</b>		
ANGLES ± 0° 30'		APVD			
MAX SURFACE ROUGHNESS 125		APVD			
ALL MACHINED SURFACES EXCEPT AS NOTED			SIZE	CODE IDENT NO.	DRAWING NO.
BREAK SHARP EDGES AND CORNERS .010 MAX			D	07101	A-3245-005
FINISH			SCALE	FIGURE # 3	SHEET

APPLICATION			REVISIONS			
QTY REQD	NEXT ASSY	USED ON	ZONE	SYM	DESCRIPTION	DATE



SCHEMATIC

NOTE: RELAYS SHOWN  
IN DE-ENERGIZED POSITION

FIGURE #4  
SCHEMATIC  
P/N 103718

ITEM OR FIND NO.	QTY REQD	NOMENCLATURE OR DESCRIPTION	MATL SPEC AND SIZE OR COMPONENT VALUE	IDENTIFYING OR PART NO.	CODE IDENT.
PARTS LIST					
ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE SPECIFIED TOLERANCES 3 PLACE DECIMALS ± 2 PLACE DECIMALS ± 1 PLACE DECIMAL ± FRACTIONS ±     ANGLES ± 0° 30' MAX SURFACE ROUGHNESS 125 ALL MACHINED SURFACES EXCEPT AS NOTED BREAK SHARP EDGES AND CORNERS .010 MAX FINISH		CONT NO CHG NO OWN RCJULIAN ENGR CHK PROD APVD APVD	ENGINEERING EXPERIMENT STATION OF THE GEORGIA INSTITUTE OF TECHNOLOGY ATLANTA, GEORGIA <b>SCHEMATIC CIRCUIT CARD P/N 103718 LOGIC CONTROL</b> SIZE CODE IDENT NO. DRAWING NO. D 07101 A-3245-005 SCALE / FIGURE # 4 SHEET		



#### IV. BOARD SPECIFICATIONS

Board No. 103717 (12 second timer) has dimensions of 2 9/16" x 3 1/8" x 1/16" thick. It should have 2 oz. copper on one side. There are 74 non-plated thru holes. Hole sizes and location are shown on Figure 5, Hole Drilling Chart. There are 28 #55 drill holes and 46 #66 drill holes. The board material meets MIL-P-13949.

Board No. 103718 (Logic Control) has dimensions of 2 9/16" x 3 1/8" x 1/16" thick. It should have 2 oz. copper on one side. There are 90 non-plated thru holes. Hole sizes and location are shown on Figure 6, Hole Drilling Chart. There are 8 #50 drill holes, 28 #55 drill holes and 54 #66 drill holes. The board material meets MIL-P-13949. Figure 7 and 8 are mechanical drawings revealing the appropriate dimensions and tooling holes for P/N 103717 and P/N 103718 respectively.

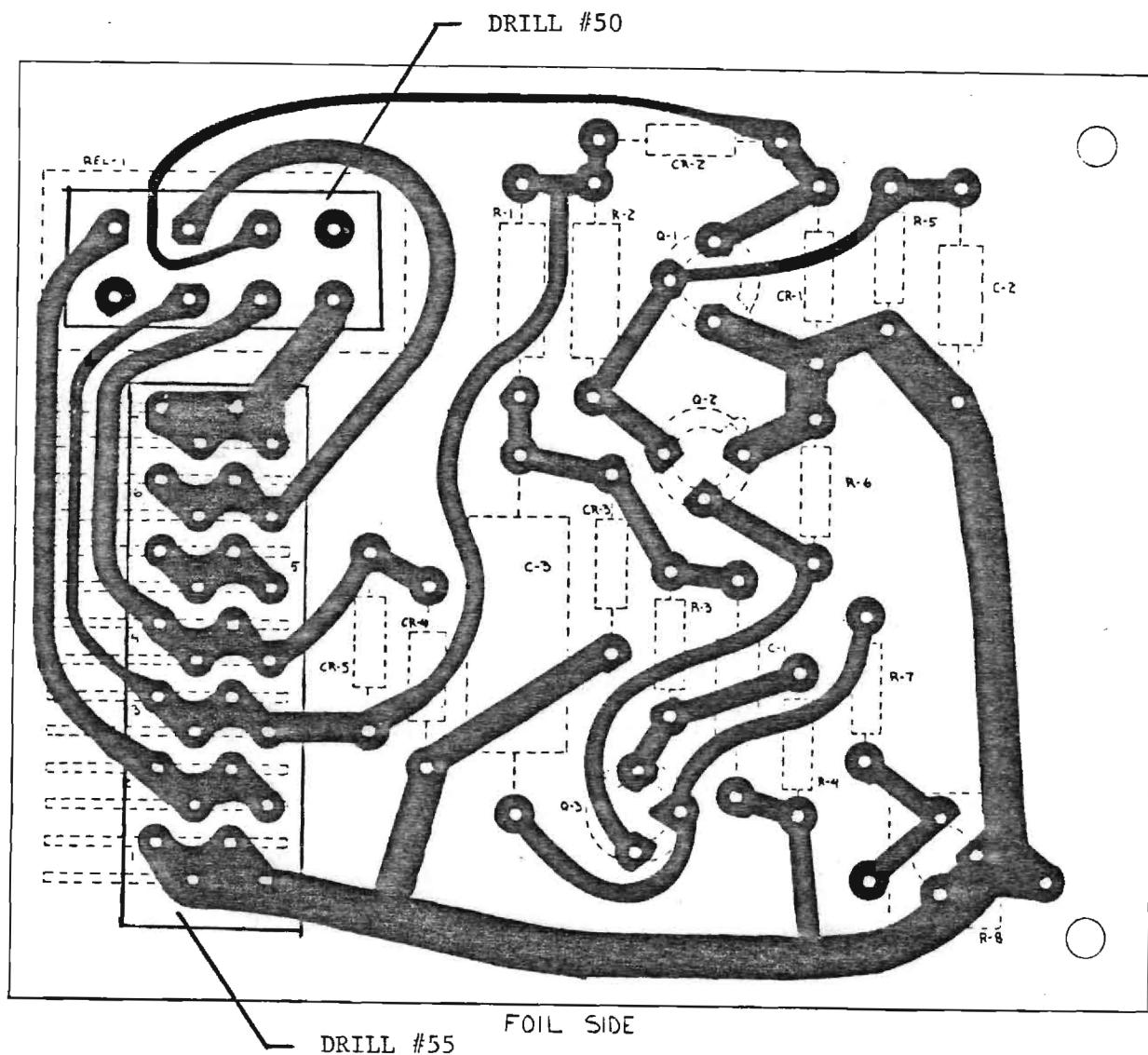
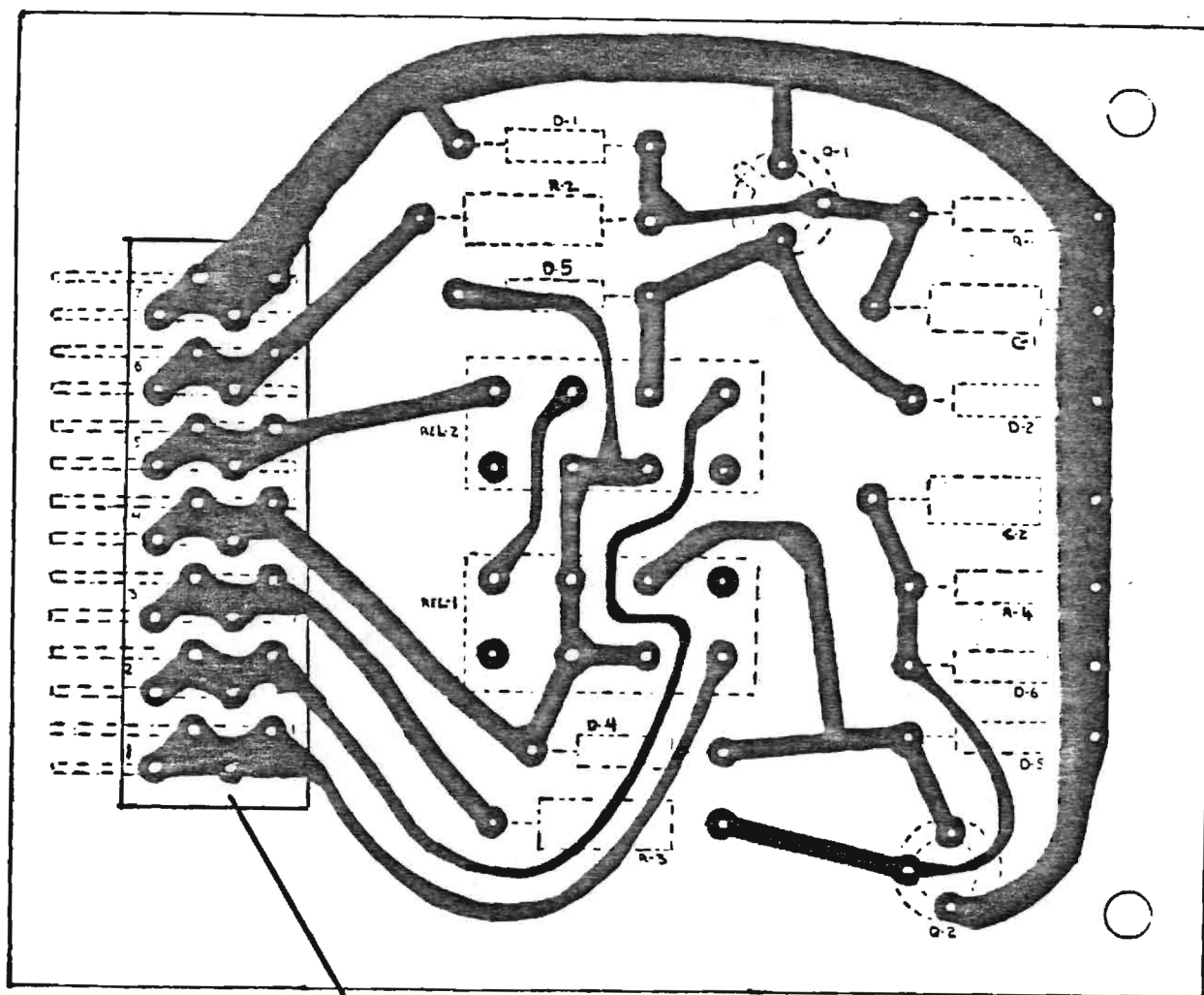


FIGURE #5 DRILL CHART FOR 103717



FOIL SIDE

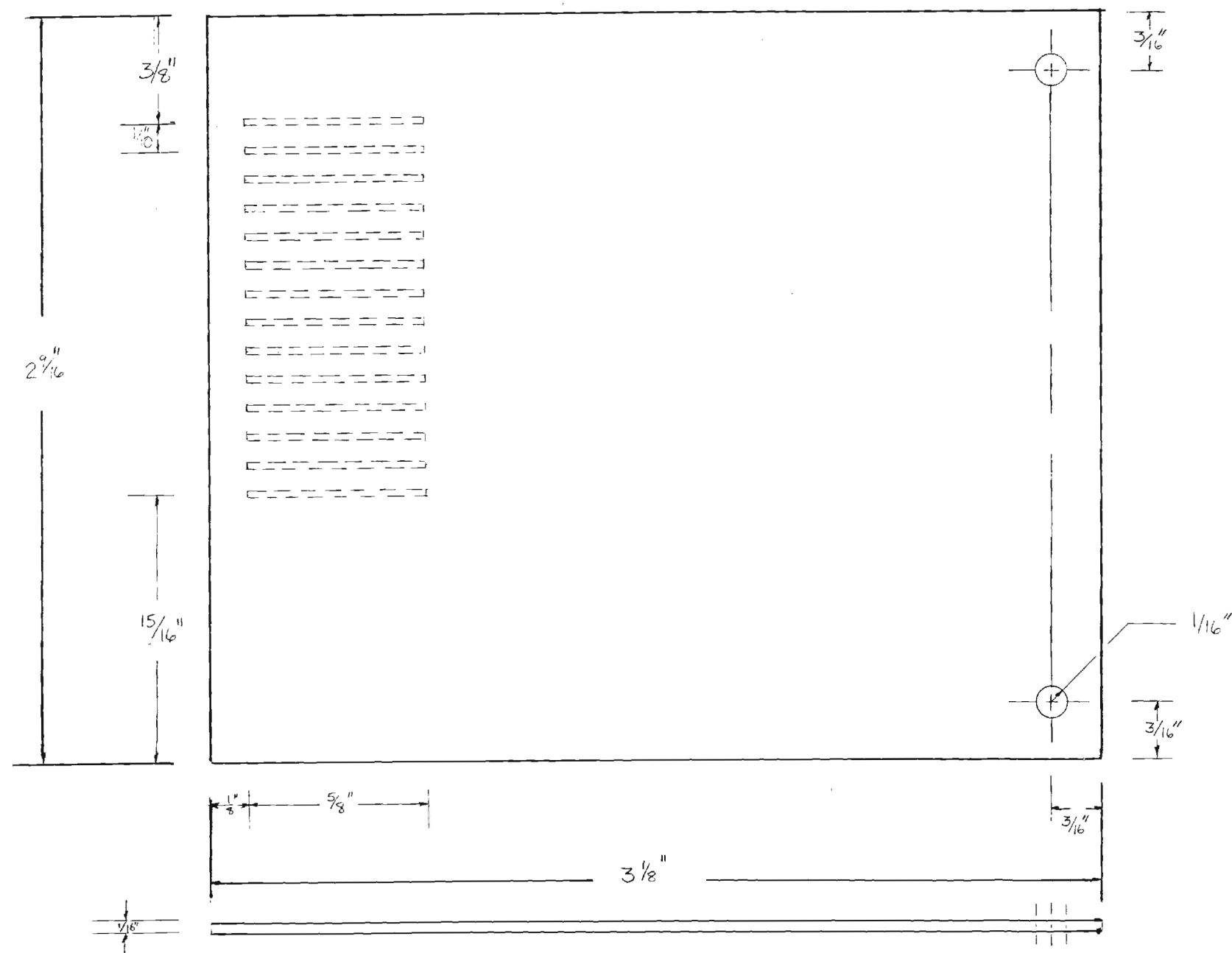
DRILL #55

ALL OTHERS DRILL #66

FIGURE #6 DRILL CHART FOR 103718

APPLICATION			REVISIONS			
QTY REQD	NEXT ASSY	USED ON	ZONE	SYM	DESCRIPTION	DATE

TOP VIEW



SIDE VIEW

FIGURE #7

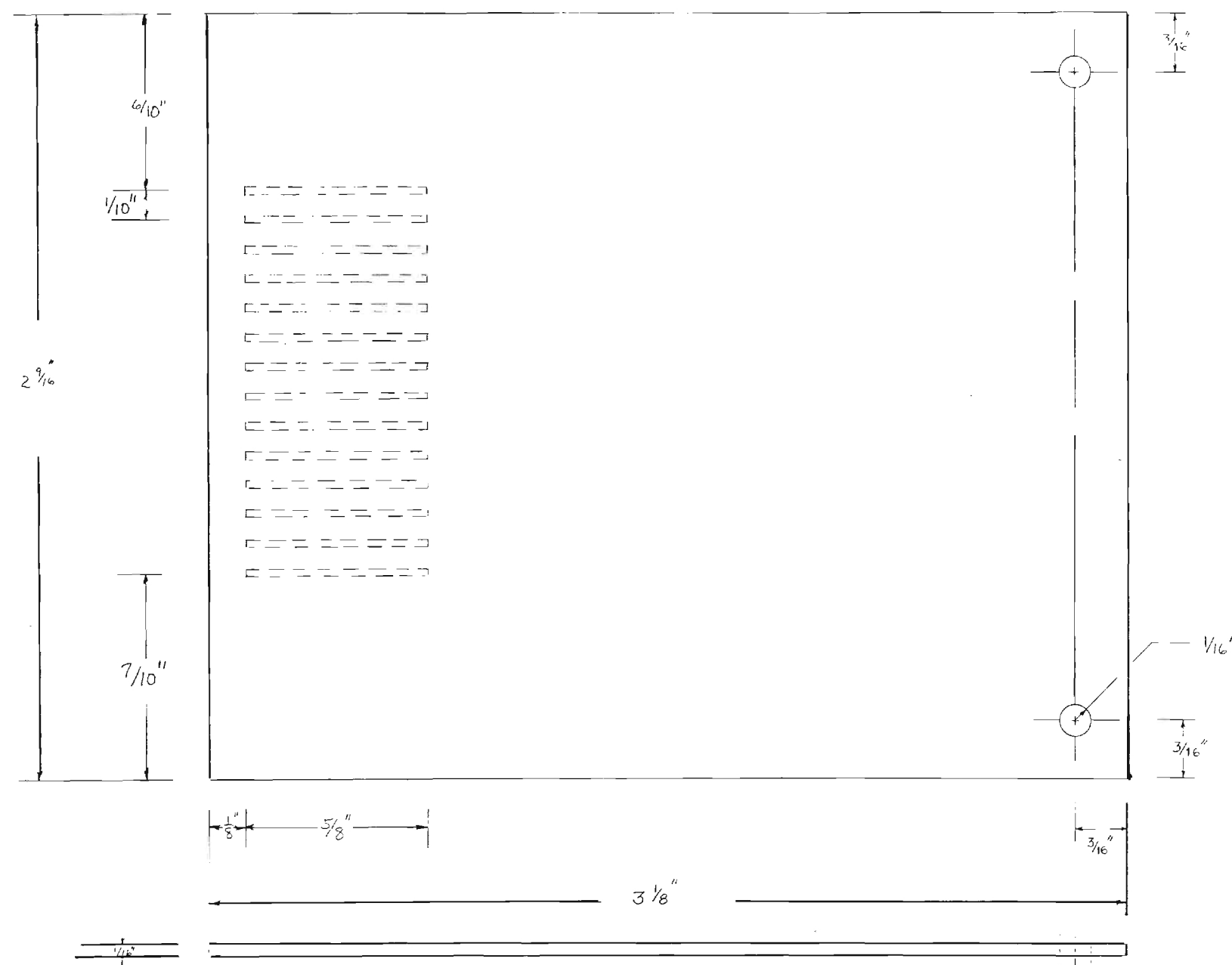
MECHANICAL DRAWING  
P/N 103717MATERIAL SPECIFICATIONS  
BOARD MATERIAL MEETS  
MIL-P-13949TOLERANCES  
± .020 IN. ON ALL DIMENSIONS

ITEM OR FIND NO.	QTY REQD	NOMENCLATURE OR DESCRIPTION	MATL SPEC AND SIZE OR COMPONENT VALUE	IDENTIFYING OR PART NO.	CODE IDENT.

ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE SPECIFIED		CONT NO		ENGINEERING EXPERIMENT STATION OF THE GEORGIA INSTITUTE OF TECHNOLOGY ATLANTA, GEORGIA			
TOLERANCES		CHG NO					
3 PLACE DECIMALS ±		DWN		MECHANICAL DRAWING CIRCUIT CARD P/N 103717 12 SECONDTIMER			
2 PLACE DECIMALS ±		ENGR					
1 PLACE DECIMAL ±		CHK					
FRACTIONS ±		PROD					
ANGLES ± 0°30'		APVD		SIZE CODE IDENT NO. DRAWING NO.			
MAX SURFACE ROUGHNESS 125		APVD					
ALL MACHINED SURFACES EXCEPT AS NOTED							
BREAK SHARP EDGES AND CORNERS .010 MAX							
FINISH							

APPLICATION			REVISIONS				
QTY REQD	NEXT ASSY	USED ON	ZONE	SYM	DESCRIPTION	DATE	APPROVED

TOP VIEW



MATERIAL SPECIFICATIONS  
BOARD MATERIAL MEETS  
MIL-P-13949.

TOLERANCES  
± .020 IN. ON ALL DIMENSIONS

ITEM OR FIND NO.	QTY REQD		NOMENCLATURE OR DESCRIPTION	MATL SPEC AND SIZE OR COMPONENT VALUE	IDENTIFYING OR PART NO.	CODE IDENT.

FIGURE #8

SIDE VIEW

MECHANICAL DRAWING  
P/N 103718

12

ALL DIMENSIONS ARE IN INCHES  
UNLESS OTHERWISE SPECIFIED

TOLERANCES


3 PLACE DECIMALS ±  
2 PLACE DECIMALS ±  
1 PLACE DECIMAL ±

FRACTIONS ±      ANGLES ± 0° 30'

MAX SURFACE ROUGHNESS 125 ✓  
ALL MACHINED SURFACES  
EXCEPT AS NOTED  
BREAK SHARP EDGES  
AND CORNERS .010 MAX

FINISH

30°	CONT NO
	CHG NO
	DWN
	ENGR
	CHK
	PROD
	APVD

 <p>ENGINEERING EXPERIMENT STATION          GEORGIA INSTITUTE OF TECHNOLOGY          ATLANTA, GEORGIA</p>		
<p>MECHANICAL DRAWING          CIRCUIT CARD P/N 103718          LOGIC CONTROL</p>		
SIZE	CODE IDENT NO.	DRAWING NO.
D	07101	A-3245-007

## V. MANUFACTURING TECHNIQUES

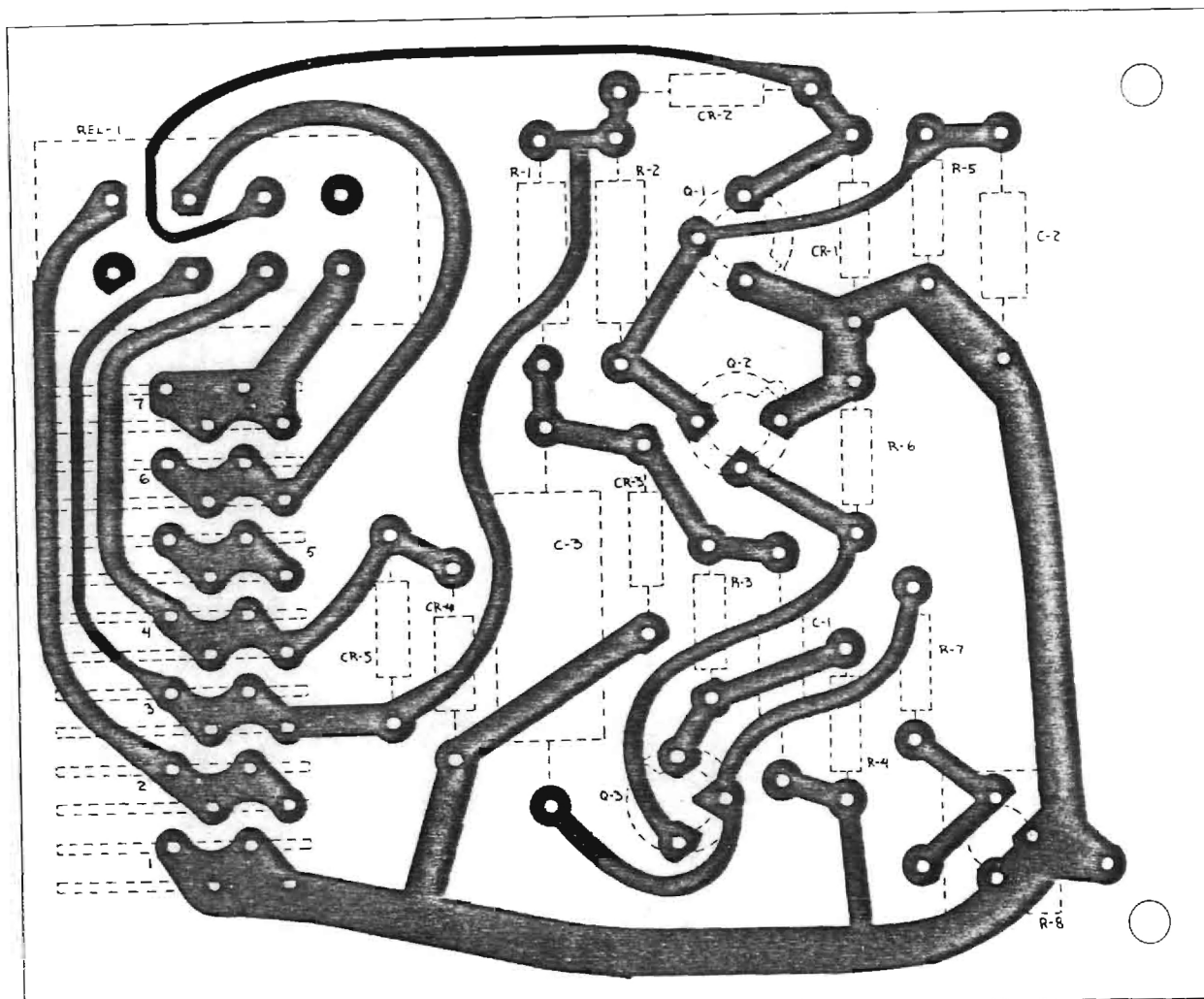
Artwork is provided which must be reduced 4 to 1 to obtain the proper negative size. Foil Side views show artwork layout (See Figures 9 and 10).

The boards shall be processed in such a manner as to be uniform in quality and be free from defects in excess of those allowed in MIL-P-55110C.

Components are to be mounted according to Figures 1 and 2.

Solder masks for each board are provided in Figures 11 and 12. The actual blue lines of all the figures referenced in this document are provided. The solder mask blue lines are scaled 4 to 1.

APPLICATION			REVISIONS			
QTY REQD	NEXT ASSY	USED ON	ZONE	SYM	DESCRIPTION	DATE



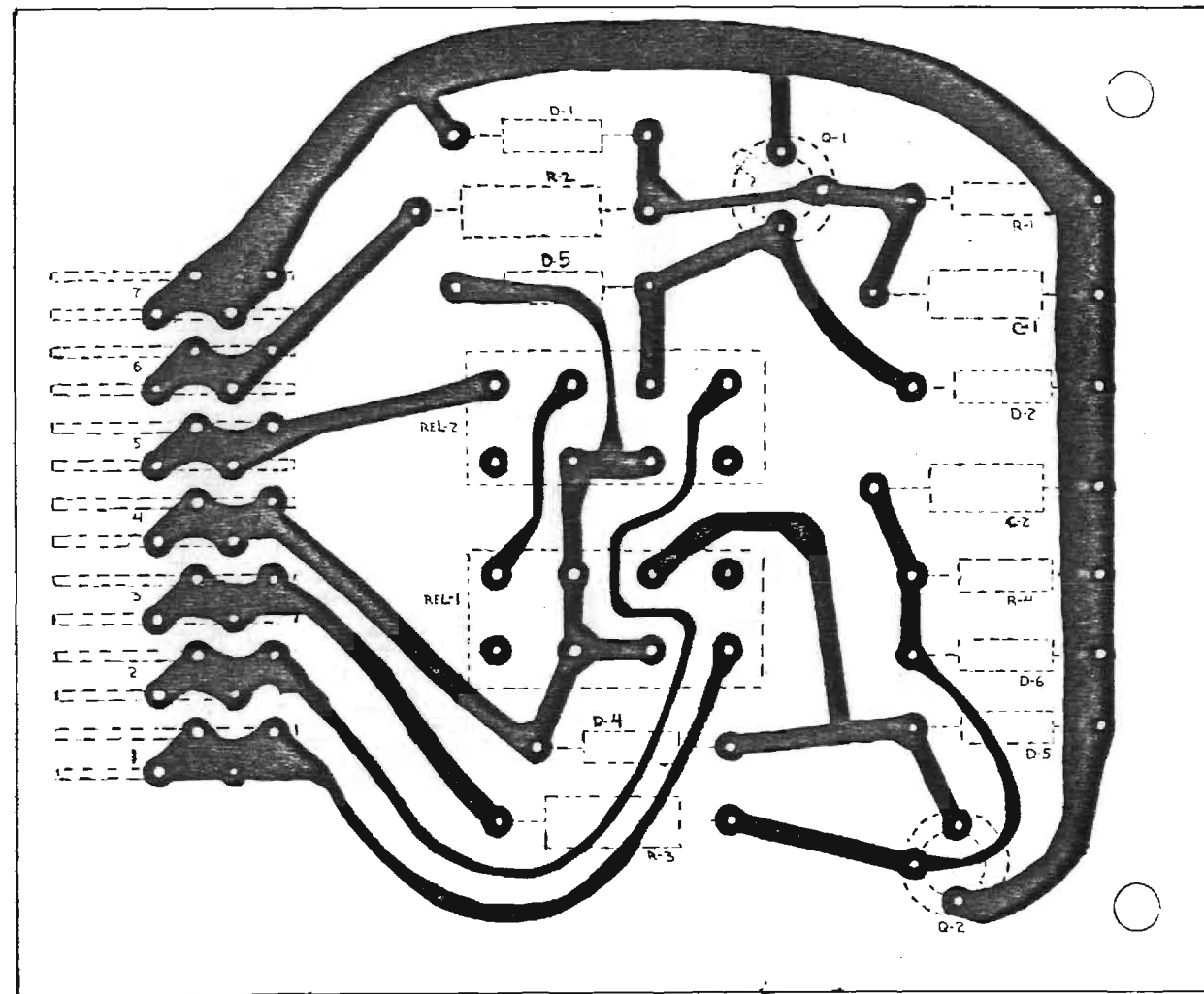
FOIL SIDE

FIGURE #9

FOIL SIDE VIEW  
P/N 103717

ITEM OR FIND NO.	QTY REQD	NOMENCLATURE OR DESCRIPTION	MATL SPEC AND SIZE OR COMPONENT VALUE	IDENTIFYING OR PART NO.	CODE IDENT.
PARTS LIST					
ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE SPECIFIED TOLERANCES 3 PLACE DECIMALS ± 2 PLACE DECIMALS ± 1 PLACE DECIMAL ± FRACTIONS ±     ANGLES ± 0°30' MAX SURFACE ROUGHNESS 125 ALL MACHINED SURFACES EXCEPT AS NOTED BREAK SHARP EDGES AND CORNERS .010 MAX FINISH			CONT NO CHG NO OWN P. WARREN 6-3-82 ENGR CHK PROD APVD APVD		
ENGINEERING EXPERIMENT STATION OF THE GEORGIA INSTITUTE OF TECHNOLOGY ATLANTA, GEORGIA FOIL SIDE CIRCUIT CARD ASSEMBLY P/N 103717			SIZE CODE IDENT NO. DRAWING NO. D 07101 A-3245-006		
SCALE /			FIGURE # 9 SHEET 1 of 1		

APPLICATION			REVISIONS			
QTY REQD	NEXT ASSY	USED ON	ZONE	SYM	DESCRIPTION	DATE



FOIL SIDE

FIGURE #10  
FOIL SIDE VIEW  
P/N 103718

ITEM OR FIND NO.	QTY REQD	NOMENCLATURE OR DESCRIPTION	MATL SPEC AND SIZE OR COMPONENT VALUE	IDENTIFYING OR PART NO.	CODE IDENT.
PARTS LIST					
ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE SPECIFIED TOLERANCES 3 PLACE DECIMALS ± 2 PLACE DECIMALS ± 1 PLACE DECIMAL ± FRACTIONS ± ANGLES ± 0°30' MAX SURFACE ROUGHNESS 125 ALL MACHINED SURFACES EXCEPT AS NOTED BREAK SHARP EDGES AND CORNERS .010 MAX FINISH		CONT NO CHG NO DWN PPW ENGR CHK PROD APVD APVD	5-26-82	ENGINEERING EXPERIMENT STATION OF THE GEORGIA INSTITUTE OF TECHNOLOGY ATLANTA, GEORGIA  FOIL SIDE CIRCUIT CARD ASSEMBLY P/N 103718  SIZE D CODE IDENT NO. 07101 DRAWING NO. A-3245-001 SCALE / FIGURE #10 SHEET 1 of 1	



APPLICATION			REVISIONS			
QTY REQD	NEXT ASSY	USED ON	ZONE	SYM	DESCRIPTION	DATE

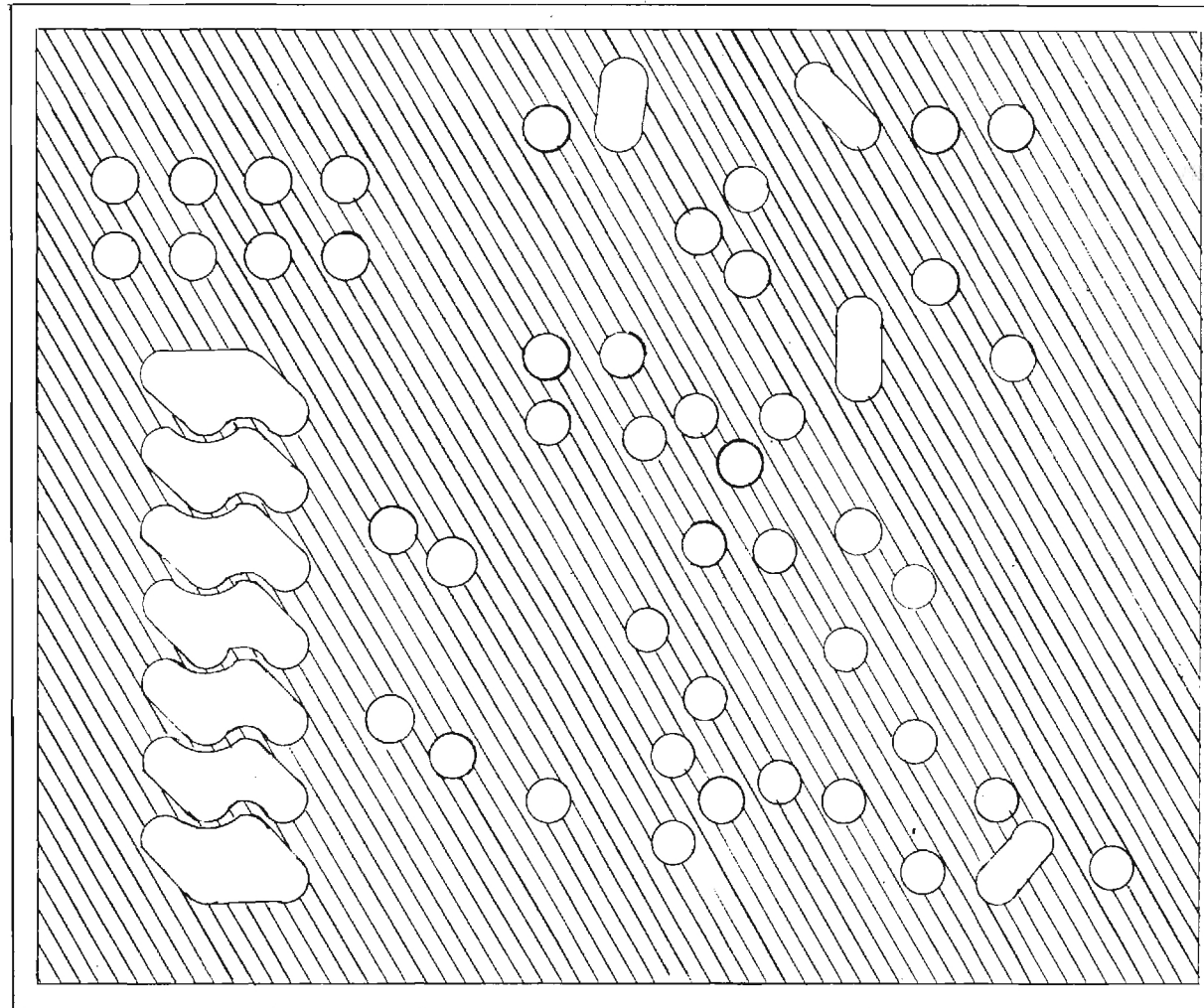


FIGURE #11

SOLDER MASK  
P/N 103717

ITEM OR FIND NO.	QTY REQD	NOMENCLATURE OR DESCRIPTION	MATL SPEC AND SIZE OR COMPONENT VALUE	IDENTIFYING OR PART NO.	CODE IDENT.
PARTS LIST					
ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE SPECIFIED		ENGINEERING EXPERIMENT STATION OF THE <b>EES</b> GEORGIA INSTITUTE OF TECHNOLOGY ATLANTA, GEORGIA			
TOLERANCES 3 PLACE DECIMALS ± 2 PLACE DECIMALS ± 1 PLACE DECIMAL ±		CONT NO CHG NO DWN <i>MR H.</i> ENGR CHK PROD APVD APVD		SOLDER MASK CIRCUIT CARD P/N 103717 12 SECOND TIMER	
FRACTIONS ± ANGLES ± 0°30'		MAX SURFACE ROUGHNESS 125 ALL MACHINED SURFACES EXCEPT AS NOTED BREAK SHARP EDGES AND CORNERS .010 MAX		SIZE CODE IDENT NO. DRAWING NO. D 07101 A-3245-009	
FINISH		SCALE 4/1		FIGURE # 11 SHEET	

APPLICATION			REVISIONS			
QTY REQD	NEXT ASSY	USED ON	ZONE	SYM	DESCRIPTION	DATE

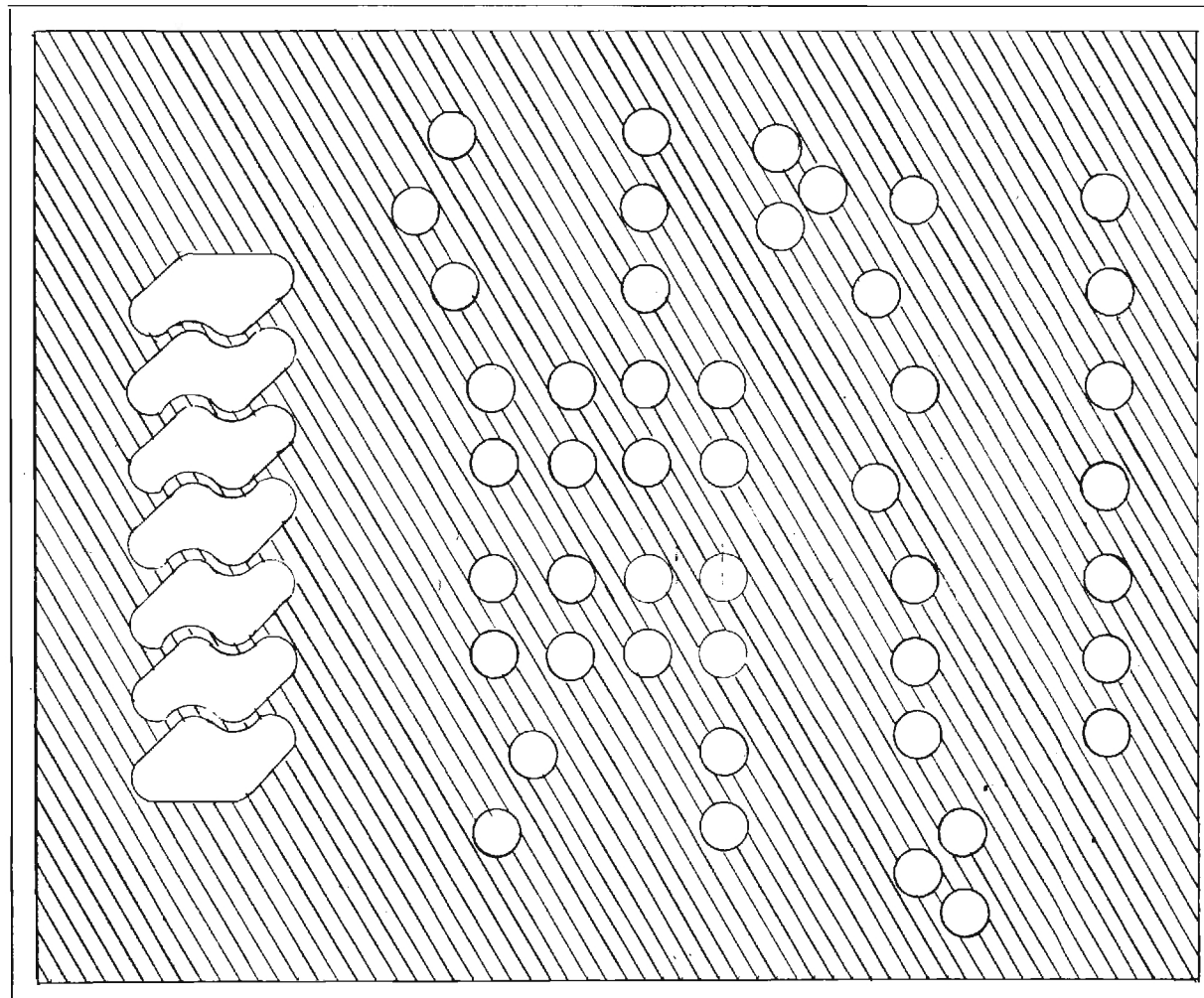


FIGURE #12

SOLDER MASK  
P/N 103718

ITEM OR FIND NO.	QTY REQD	NOMENCLATURE OR DESCRIPTION	MATL SPEC AND SIZE OR COMPONENT VALUE	IDENTIFYING OR PART NO.	CODE IDENT.
PARTS LIST					
ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE SPECIFIED TOLERANCES 3 PLACE DECIMALS ± 2 PLACE DECIMALS ± 1 PLACE DECIMAL ± FRACTIONS ±      ANGLES ± 0°30' MAX SURFACE ROUGHNESS 125 ALL MACHINED SURFACES EXCEPT AS NOTED BREAK SHARP EDGES AND CORNERS .010 MAX FINISH		CONT NO CHG NO DWN <i>MR AL</i> ENGR CHK PROD APVD APVD	ENGINEERING EXPERIMENT STATION OF THE <b>EES</b> GEORGIA INSTITUTE OF TECHNOLOGY ATLANTA, GEORGIA <b>SOLDER MASK</b> CIRCUIT CARD P/N 103718 LOGIC CONTROL SIZE D CODE IDENT NO. 07101 DRAWING NO. A-3245-010 SCALE 4/1 FIGURE #12 SHEET		

## VI. TROUBLESHOOTING PROCEDURES

### 1. Visual Inspection of printed circuit boards and components.

The suspect board should be removed from the motherboard and visually inspected for open traces, imperfect solder joints, broken leads, or overheated components. Specifically, on P/N 103717 (12 second timer), board failure has been attributed to open traces from pin 4 to the relay and from the relay to pin 2. Simple continuity checks can be performed to verify most of these problems.

### 2. Component Testing.

Suspect components on the board should be removed and out-of-circuit tests performed to reveal component breakdown. These out-of-circuit tests are described in Section VII. If a particular component continues to break down after replacement, then external factors to the board can be causing the malfunctions.

## VII. COMPONENT TESTING

This section describes out-of-circuit ohmmeter tests that can be performed on resistors, capacitors, diodes, and transistors to determine faulty components (NOTE: resistors, capacitors, diodes, and other axial lead components require only one lead to be removed from the circuit). Since the basis of these tests are to measure resistance, it is important not to touch the ohmmeter leads. There is no danger of shock, but the body resistance as a parallel path will affect the accuracy of the reading.

### 1. Resistors

Connect the resistance being measured between the ohmmeter leads. The ohmmeter should read the appropriate resistance specified by its color code within a given tolerance. The construction of resistors is such that the trouble they usually develop is an open, with infinitely high ohms.

### 2. Capacitors

When using an ohmmeter to check capacitors of greater than about 0.01  $\mu$ fd, the highest ohms range is preferable. Connect the ohmmeter leads across the capacitor. For a good capacitor, the meter pointer moves quickly toward the low-resistance side of the scale and then recedes toward infinity (charging action). The reading when the pointer stops moving is the insulation resistance of the capacitor, which is normally very high. If the ohmmeter reading immediately goes practically to zero and stays there, the capacitor is short-circuited. If the capacitor shows no charging action, but just reads very high resistance, it may be open. Some precautions must be remembered, however, since very high resistance is a normal condition for capacitors. Reverse the ohmmeter leads to discharge the capacitor, and check it again. If the capacitor shows charging, but the final resistance reading is appreciably less than normal, the capacitor is leaky. Such capacitors are particularly troublesome in high-resistance circuits. When checking electrolytics, reverse the ohmmeter leads and take the higher of the two readings.

### 3. Diodes

A diode should have at least 100 times more resistance in the reverse directions compared with the forward resistance. Just connect the ohmmeter across the diode in one polarity, and then reverse the leads for the opposite polarity. A silicon diode has practically infinite resistance in the reverse direction. When the resistance is very high in both directions, the diode is open. When the resistance is very low in both directions, the diode is shorted.

#### 4. Transistors

Check the resistance between base and collector and reverse the leads. Do the same for base and emitter. You should get a very high reading when the junction is reverse-biased and a very low reading when the junction is forward-biased. These tests really check each transistor junction as a diode. The actual reading in ohms depends upon your ohmmeter, the range selected, and the type of transistor. For conclusive tests, make a comparison with another transistor of the same type that is known to be good. It is helpful to realize that the reverse resistance of a silicon junction is usually infinite. Obtaining proper results of this test is a necessary but not sufficient condition for an operable standard transistor. Loss of gain and impaired breakdown voltages will not be apparent.

## VIII. CIRCUIT CARD FUNCTIONAL ANALYSIS

1. The functional block diagram for P/N 103717 (see Figure 13) shows general circuit operation of the 12 second timer that is used to control the power source which activates the flush valve. The circuit schematic shown in Figure 3 reveals further detail. When a potential is applied across pins 1 and 3 by a momentary pushbutton switch, transistor Q1 conducts immediately energizing REL-1 which latches Pin 6 to 7 and Pin 2 to 4. These connections are assumed to activate the flushing mechanism.

The capacitor C1 and resistors R1, R3, R4 provide a debouncing network for the actuating switch, these components have approximately a 20 millisecond time constant. Capacitor C2 and resistor R5 prevent chatter in the relay and have a time constant of approximately 15 milliseconds.

The resistors R1, R3, and R4 form a voltage divider to select 62% of the applied voltage and apply it to the network containing resistors R7 and R8 and capacitor C3. These resistors also provide a threshold of 31% of the applied voltage to the emitter of transistor Q3. Capacitor C3 charges toward the 62% voltage with a time constant adjustable between 10.3 and 20.7 seconds. When capacitor C3 has charged sufficiently, it causes transistor Q3 to conduct, as the remaining voltage across resistors R7 and R8 drops. Resistor R8 may be adjusted to cause the interval to be exactly the desired time delay (usually 12 seconds). When transistor Q3 starts conducting, base current is provided to Q2 causing conduction. Transistor Q2's conduction causes the base potential of transistor Q1 to be drawn low which cuts transistor Q1 off. When transistor Q1 stops conducting relay REL-1 de-energizes opening the connections between Pins 6 and 7 and Pins 2 and 4 which deactivates the flushing mechanism. Capacitor C3 recycles through resistor R3 and the base-emitter junction of transistor Q3 permitting a new delay cycle to start about 0.1 second after the previous one.

Diode CR2 conducts the coil current until it decays to prevent damaging voltage kickbacks to Q1. Diode CR1 provides added protection against reverse transients for Q1.

Diodes CR4 and CR5 serve apparently as anti-reverse polarity protectors. External fusing will be blown by the conduction of these diodes if an error in power polarity is made.

Diode CR3 serves to protect the electrolytic capacitors C3 and C1 from damage from reverse polarity.

2. The functional block diagram for P/N 30718 (see Figure 14) shows the general operation of the control logic board. More specific information can be obtained from the schematic (see Figure 4) and the following description of component function.

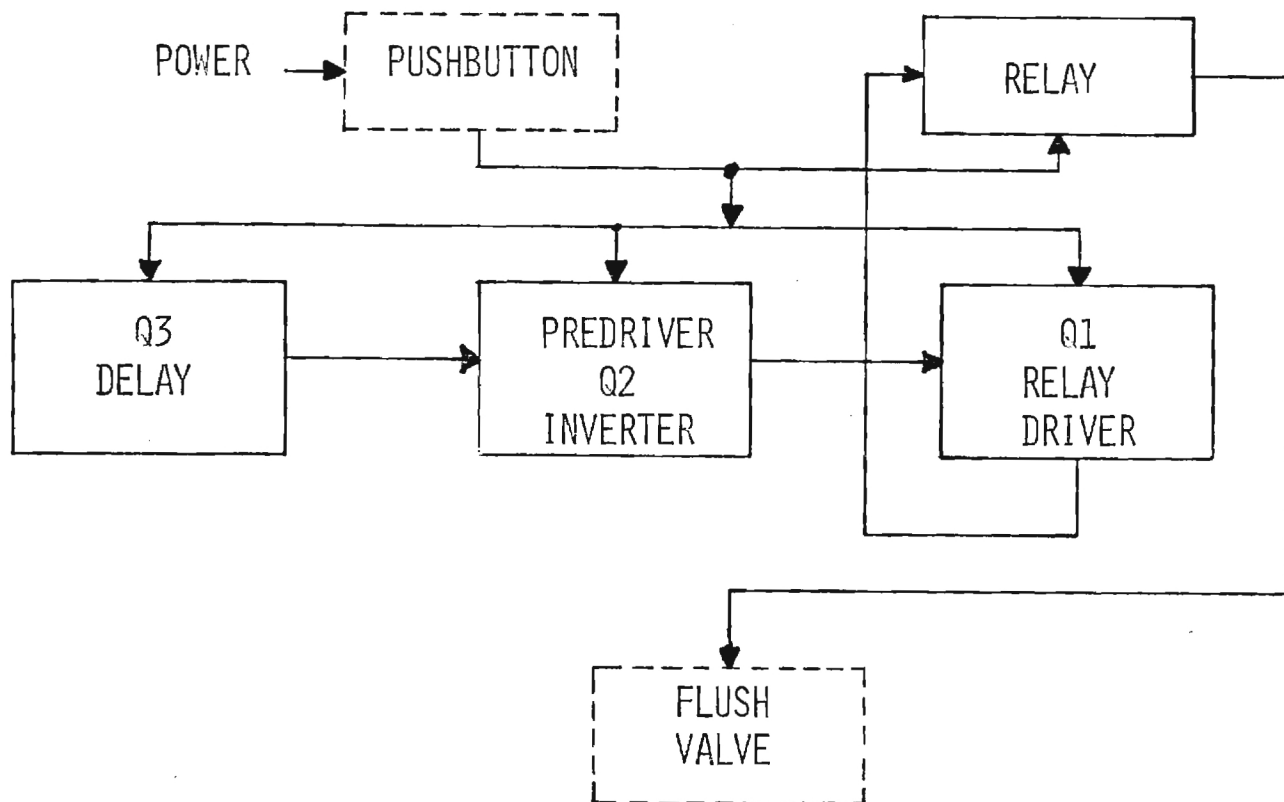


FIGURE 13. FUNCTIONAL BLOCK DIAGRAM P/N 103717

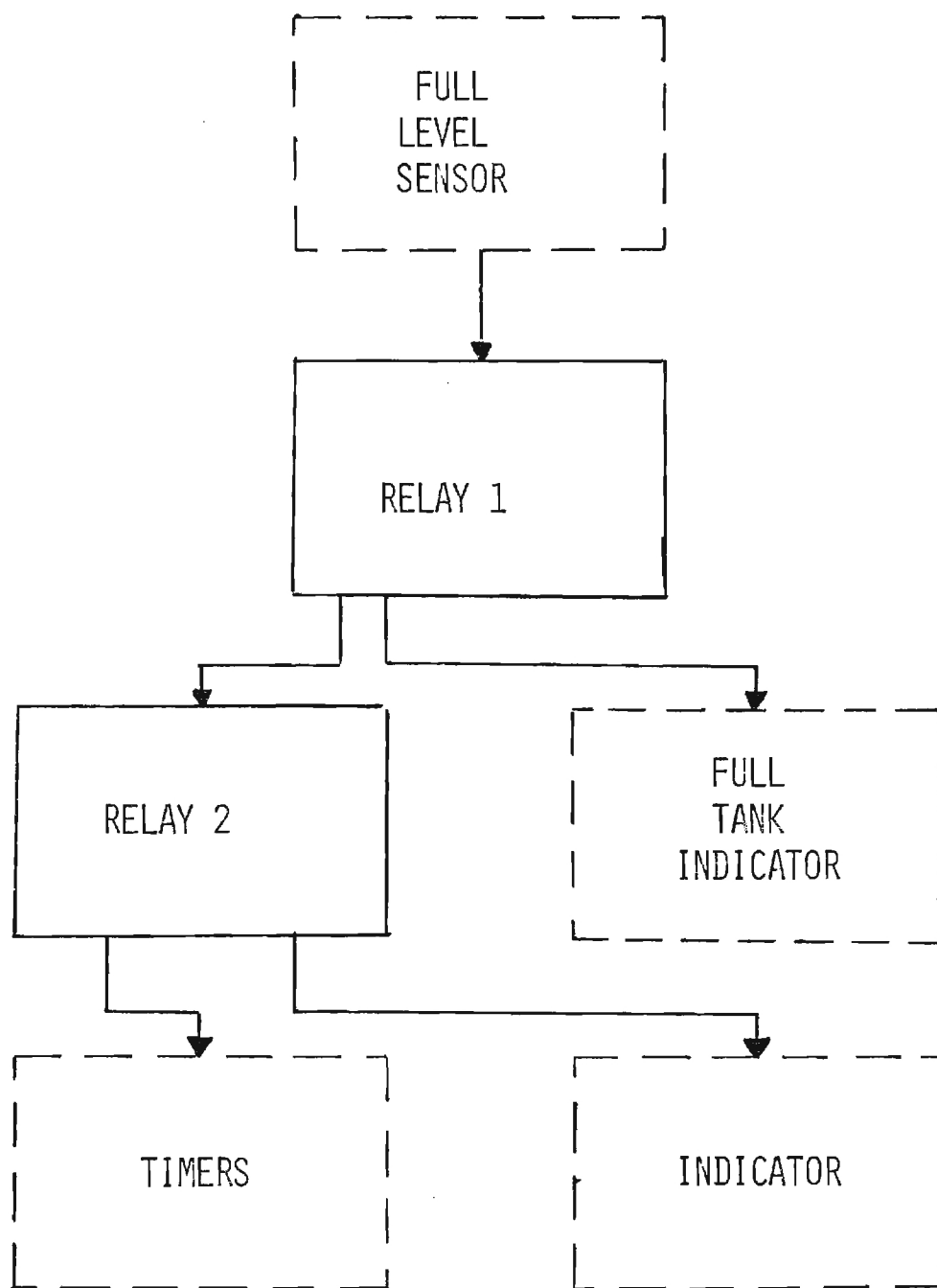


FIGURE 14. FUNCTIONAL BLOCK DIAGRAM P/N 103718



When pins 3 and 4 receive a 26 volt level transistor, Q2 turns on and relay 1 energizes providing 26 volts to pins 1 and 2. When pin 6 receives a 26 volt level transistor Q1 turns on allowing relay 2 to energize, if 26 volts is present on pins 3 and 4 (relay 2 will not energize unless relay 1 is in an energized state). When relay 2 energizes it provides 26 volts to pin 5 and opens the circuit to pin 2.

Resistors R2 and R1 provide a voltage divider for Q1 and resistors R3 and R4 provide a voltage divider for Q2.

Diodes D3 and D4 conduct coil current to prevent damaging voltage kickbacks to the transistors. Diodes D1 and D6 provide emitter-base reverse bias protection and diodes D2 and D5 provide collector-base protection for transistors Q1 and Q2 respectively.

Presently there is no connection at pin 6, but applying 26 volts to pin 6 triggers an abort mechanism associated with transistor Q1 and relay 2 which deactivates the timing circuitry and prevents flushing, and provides 26 volts on pin 5 which is assumed to be an indicator of some sort.

## IX. Proposed Improvements

There are two major deficiencies with the existing printed circuit cards in the Electronic Control Box for the Bare Base Chemical Toilet.

1. The printed circuit contacts used on the cards cost approximately \$85 per board.
2. The existing circuit cards use out-dated design techniques to perform their logic and timing functions.

Using state-of-the-art electronic design techniques the 12-second timers (P/N 103717) and the logic control card (P/N 103718) could be reduced down to one circuit card. The new board could fit in the present Electronic Control Box in place of the existing motherboard. By so doing, the two deficiencies stated above would be alleviated.